

L Number	Hits	Search Text	DB	Time stamp
-	306	451/526.ccls.	USPAT;	2002/12/10 13:20
			US-PGPUB;	
			EPO; JPO	
-	8820	(polish polishing planarize planarizing planarization) with	USPAT;	2002/12/10 11:37
		(conduct conductive electrode electrodes)	US-PGPUB;	
1			EPO; JPO	
-	1530	((polish polishing planarize planarizing planarization) with	USPAT;	2002/12/10 11:38
		(conduct conductive electrode electrodes)) with (pad article	US-PGPUB;	
		body device)	EPO; JPO	2002/12/10 11:39
-	814		USPAT; US-PGPUB:	2002/12/10 11.39
		(conduct conductive electrode electrodes)) with (pad article body device)) with (substrate wafer semiconductor)	EPO: JPO	
	142		USPAT:	2002/12/10 19:40
-	142	45 1/\$.ccis. and pad with (conductive electrode)	US-PGPUB:	2002/12/10 19.40
			EPO: JPO	
	183	polishing near2 pad with (conductive electrode)	USPAT:	2002/12/10 19:41
-	103	pointing field pad with (conductive electrody)	US-PGPUB:	2002:12:10
			EPO; JPO	
<u>-</u>	15	("5222329" "5242524" "5308438" "5337015" "5413941"	USPAT	2002/12/10 19:46
		"5439551" "5738562" "5830041" "5876265" "5904608"		
		"5944580" "5948700" "6007405" "6010538"	İ	
		"6015754").PN.		
-	15	("5222329" "5242524" "5308438" "5337015" "5413941"	USPAT	2002/12/10 19:51
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		"6015754").PN.		